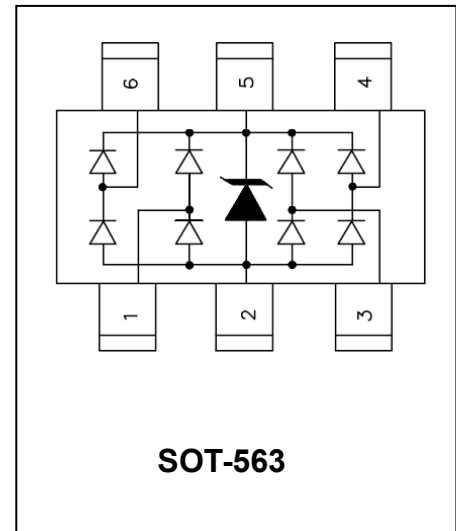


Features

- ◆ 150 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects five I/O lines
- ◆ Small package for use in portable electronics
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

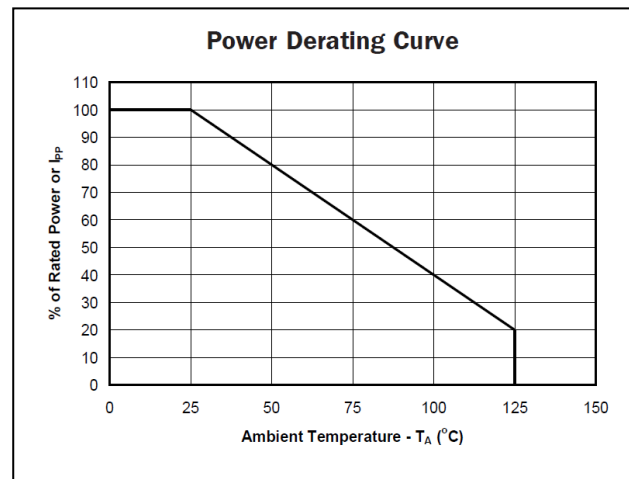
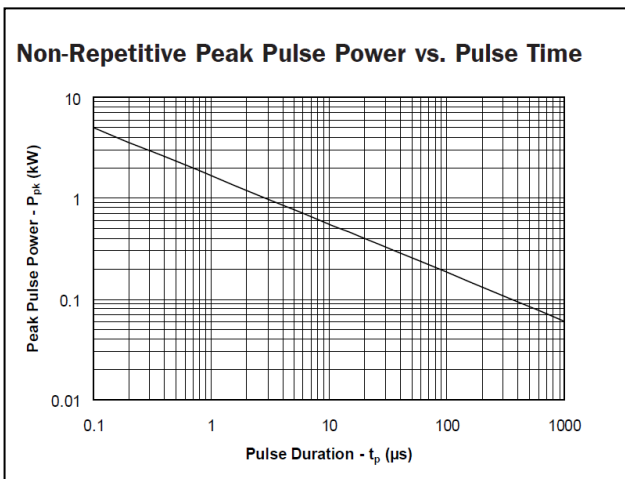
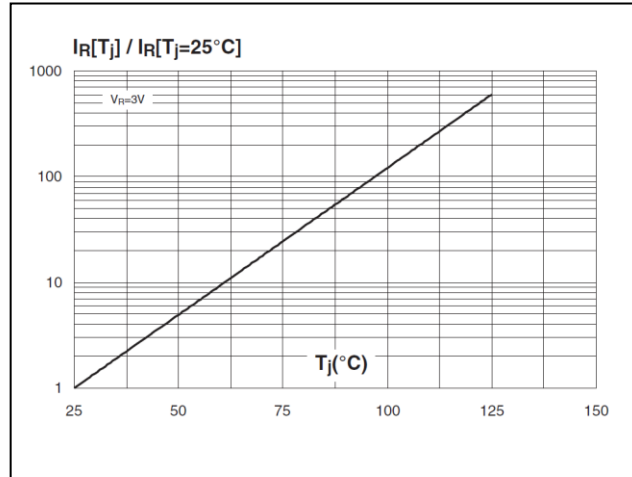
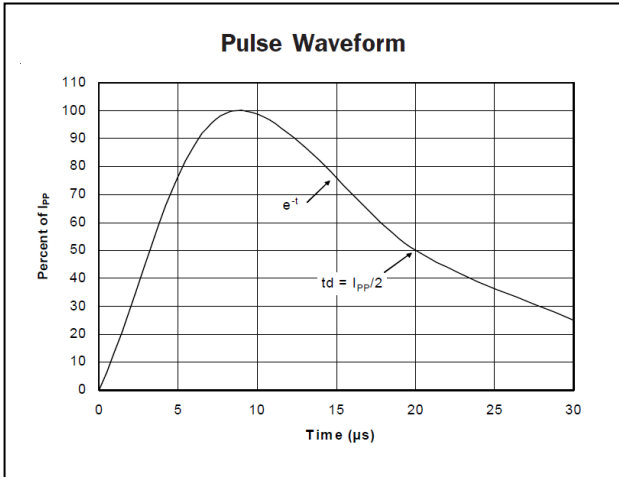
Maximum Rating @ Ta=25°C unless otherwise specified

Symbol	Parameter	Ratings	Units
P _{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	150	Watts
T _L	Lead Soldering Temperature	260(10sec.)	°C
T _J	Operating Temperature	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +150	°C

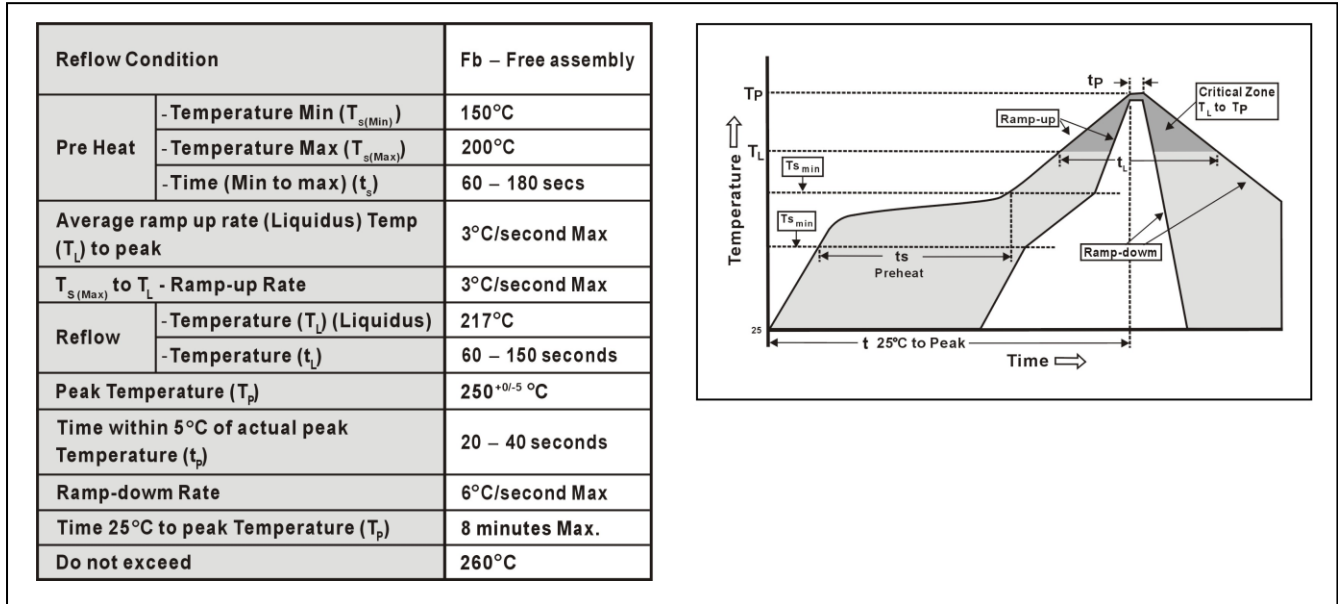
Electrical Characteristics@ Ta=25°C unless otherwise

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{RWM}	Reverse Working Voltage	Any I/O to Ground			5.0	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA, Any I/O to Ground	6.0			V
I _R	Reverse Leakage Current	V _{RWM} = 5V, Any I/O to Ground			1	μA
V _C	Clamping Voltage	I _{PP} = 1A, t _p = 8/20μs, any I/O pin to Ground			9.8	V
		I _{PP} = 3A, t _p = 8/20μs, any I/O pin to Ground			15	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz, between I/O pins		0.3	0.5	pF
		V _R = 0V, f = 1MHz, any I/O pin to Ground		0.5	0.8	pF

Typical Characteristics @ Ta=25°C unless otherwise specified



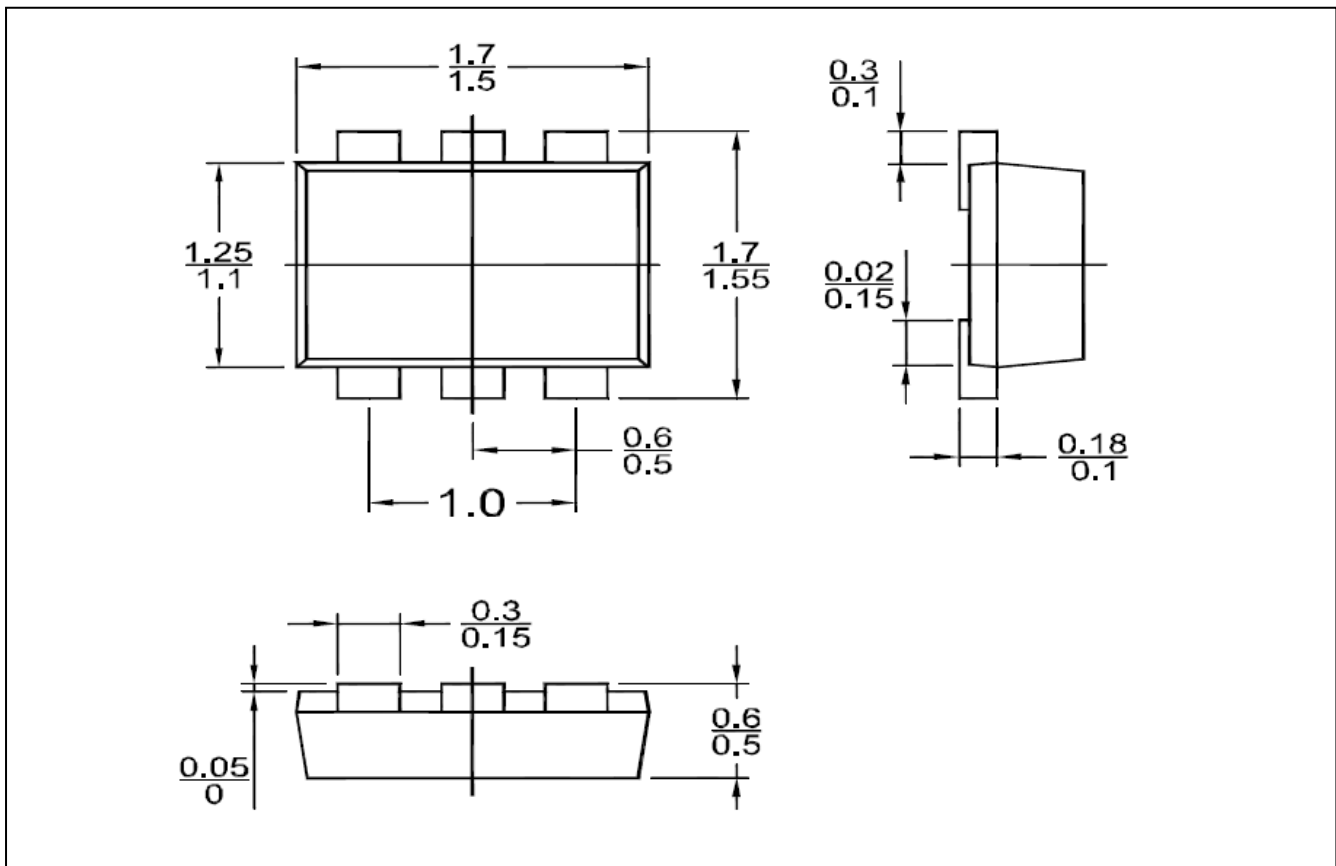
Soldering Parameters



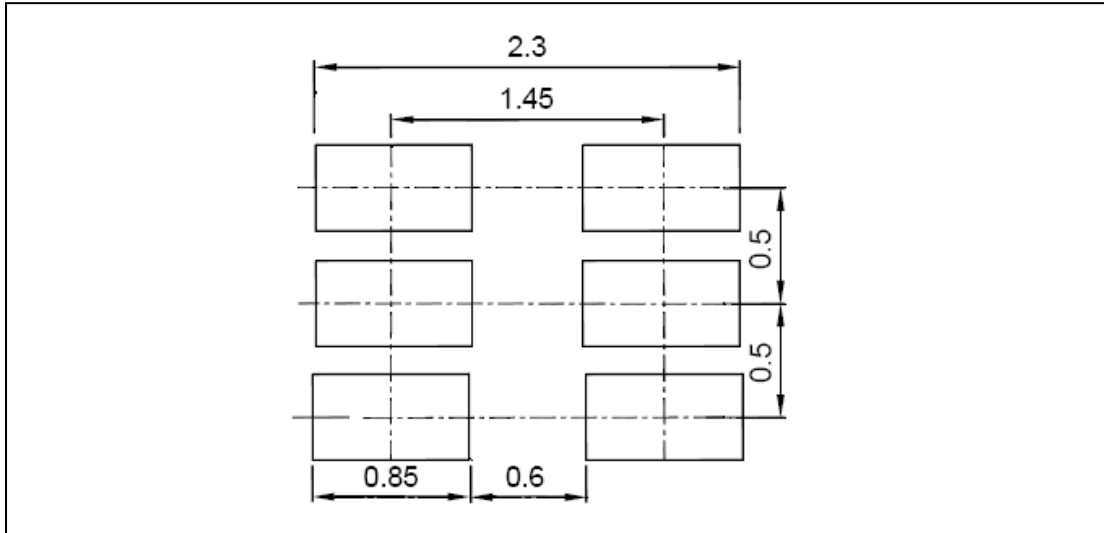
Package Outline

Plastic surface mounted package

SOT-563



Soldering Footprint



Package And Marking Information

Device	Package	Shipping	Reel Size
ZX5605UC	SOT-563	3000/Reel	7 inch